



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20240610000.1

**Qualification of TI Malaysia as an additional assembly site for select devices
Change Notification / Sample Request**

Date: June 10, 2024

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240610000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA226AIDGSR	NULL
INA226AIDGST	NULL
INA230AIDGST	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240610000.1	PCN Date:	June 10, 2024
Title:	Qualification of TI Malaysia as an additional assembly site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	September 08, 2024	Sample requests accepted until:	July 10, 2024*

***Sample requests received after July 10, 2024 will not be supported.**

Change Type:

<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Malaysia as an additional Assembly site for the list of devices below:

Constructions differences are as follows:

	ASESH	HFTF	MLA
Mold Compound	SID#EN2000515	SID#R-30	4211880
Mount Compound	SID#EY1000063	SID#A-18	4147858
Bond Wire composition/diameter	Au, 1.0 mil	Au, 1.0 mil	Au, 0.96 or Cu, 1.0 mil

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASESH	ASH	CHN	Shanghai
HFTF	HFT	CHN	Hefei
MLA	MLA	MYS	KUALA LUMPUR

Sample product shipping label (not actual product label):



Product Affected:

INA226AIDGSR INA226AIDGST INA230AIDGSR INA230AIDGST

Information Selective Discourse

Qualification Report

MLA/TIM 10DGS A/T Offload - HPA07 Commercial AU & PCC wire

Approve Date 16-May-20

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: MAX25400000	Qual Device: MAX25400001	QBS Reference: MAX25400000	QBS Reference: MAX25400001	QBS Reference: MAX25400002	QBS Reference: MAX25400003	QBS Reference: MAX25400004	QBS Reference: MAX25400005	QBS Reference: MAX25400006	QBS Reference: MAX25400007	QBS Reference: MAX25400008	QBS Reference: MAX25400009	QBS Reference: MAX25400010
EISD	E2	EISD CDM	-	750 Volts	-	-	-	-	1/0	-	1/0	-	-	-	-	-	-
EISD	E2	EISD HBM	-	1000 Volts	1/0	1/0	-	-	-	-	-	-	-	-	1/0	1/0	-
EISD	E2	EISD HBM	-	2000 Volts	-	-	-	1/0	1/0	1/0	-	-	-	-	-	1/0	-
LU	E4	Latch-Up	Per JEDEC78	-	1/0	1/0	1/0	1/0	1/0	1/0	-	1/0	-	-	1/0	1/0	1/0
CHAR	EE	Electrical Characterization Parameter Measurability	-	1/00	1/00	-	-	-	-	-	-	-	-	-	1/00	1/00	1/00
CHAR	EE	Electrical Characterization Cyclic-1.67 Room, hot and cold	-	-	-	3/00	1/00	1/00	-	-	3/00	-	-	-	-	3/00	-
FTY	EE	Final Test Yield	-	-	-	-	-	-	-	-	-	1/0	1/0	-	-	-	-

- QBS Qual B Similarity
- Qual Device (MAX25400000) is qualified at MSL1 260C
- Qual Device (MAX25400001) is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSIL as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 115C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 185C/240 Hours
- The following are equivalent HTSIL options based on an activation energy of 0.7eV: 180C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JEDEC78: 45C/125C/700 Cycles and 45C/150C/800 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

TI Qualification ID: R-CHG-2308-029

For alternate parts with similar or improved performance, please visit the product page on TI.com

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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